

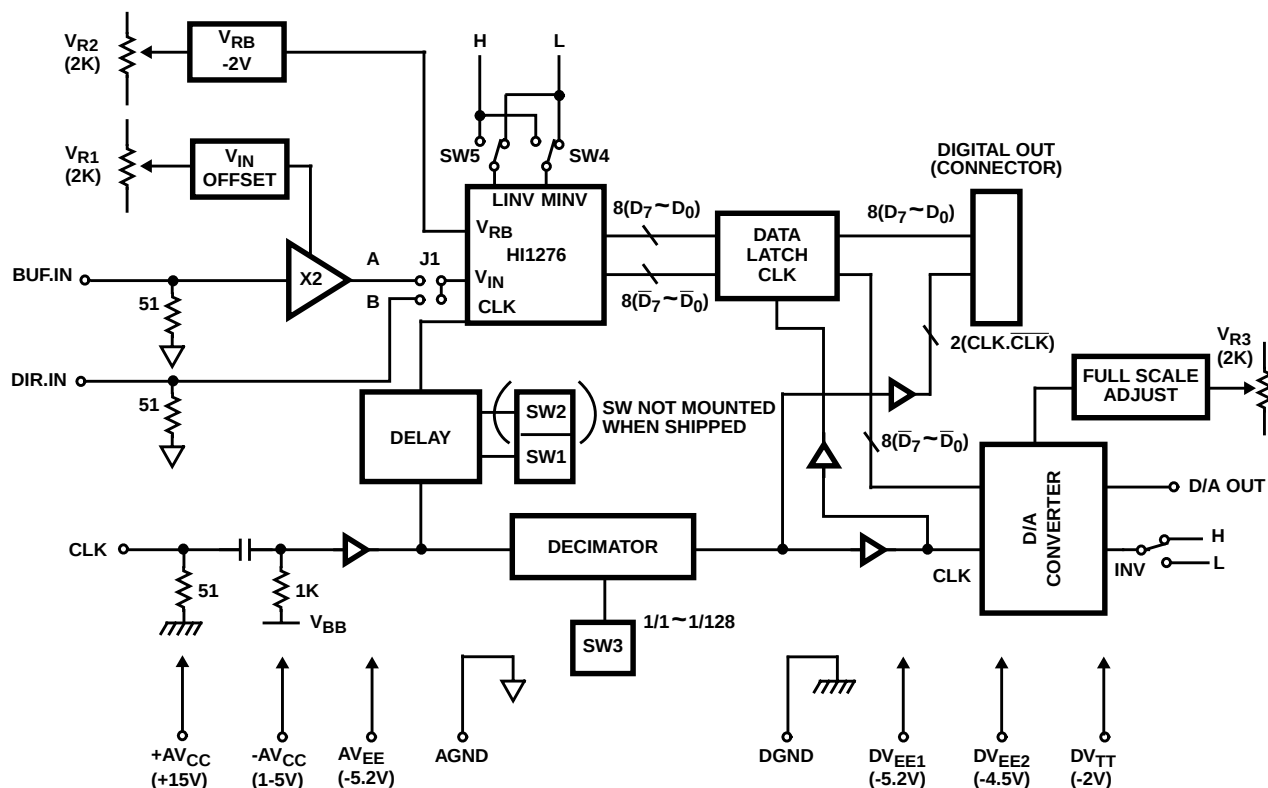
Description

The HI1276 evaluation board is a tool for customers to evaluate the performance of the HI1276AIL, an 8-bit, 500MSPS, high-speed A/D converter. In addition to features such as a reference voltage generator, this evaluation board is equipped with input voltage offset capability, a clock decimator, output data latches, a 10-bit high-speed DAC, and a 20-pin cable connector for digital outputs. This evaluation board is designed to facilitate evaluation of the HI1276AIL.

Features

- 8-Bit Resolution
- Maximum Conversion Rate 500MSPS
- Supply Voltages -5.2V, -4.5V, -2.0V, +15V, -15V
- Clock Level Converter Sine Wave to ECL Level Signal
- Reference Voltage Adjustment Circuit for A/D Converter
- Built-In Clock Frequency Decimation Circuit . . . 1/1 to 1/128

Block Diagram



Application Note 9332

SUPPLY CURRENT

ITEM	MIN	TYP	MAX	UNIT
$A_{VEE} + D_{VEE1}$ (-5.2V)	-	0.6	0.9	A
D_{VEE2} (-4.5V)	-	1.0	1.5	A
D_{VTT} (-2.0V)	-	0.75	1.2	A
$-AV_{CC}$ (-15.0V)	-	60	100	mA
$+AV_{CC}$ (+15.0V)	-	50	100	mA

ANALOG INPUT

ITEM	MIN	TYP	MAX	UNIT
Input Voltage (BUF. IN) (Note 1)	-0.5	-	+0.5	V
Input Voltage (DIR. IN) (Note 1)	-2.0	-	0	V
Input Impedance	-	50	-	Ω

NOTE: For the analog input method, see Section 3 of "Adjustment Methods and Notes on Operation".

CLOCK INPUT (CLK)

ITEM	MIN.	TYP	MAX	UNIT
Input Voltage (Peak to Peak)	-	1.0	-	V_{P-P}
Input Impedance	-	50	-	Ω

OUTPUT CODE TABLE

	MINV (SW5)	0	0	1	1
	LINV (SW4)	0	1	0	1
V_{IN}	0V	111...11	100...00	011...11	000...00
	.	111...10	100...01	011...10	000...01
	.	.	.	.	.
	.	.	.	.	.
	.	.	.	.	.
	.	100...00	111...11	000...00	011...11
	.	011...11	000...00	111...11	100...00
	.	.	.	.	.
	.	.	.	.	.
	.	.	.	.	.
	.	000...010	011...10	100...01	111...10
	-2V	000...00	011...11	100...00	111...11

1: ECL High Level

0: ECL Low Level

Adjustment Methods and Notes on Operation

1. V_{IN} offset (V_{R1}) - Centers the BUF. IN signal range (0V center assumed) within the A/D converter input range.
2. A/D Full Scale (V_{R2}) - Adjusts the A/D converter V_{RB} voltage (-2V typical).
3. J1 jumper wire selects the analog input pins BUF. IN or DIR. IN. (See Block Diagram.)

ANALOG INPUT METHOD	A	B	OFFSET
When Using BUF. IN	Shorted	Open	Adjusted by V_{R1}
When Using DC-Coupled DIR. IN Input	Open	Shorted	Input Offset Signal
When Using AC-Coupled DIR. IN Input	1k Ω	0.1 μ F	Adjusted by V_{R1}

4. D/A full scale (V_{R3}) - Adjusts the D/A output full scale voltage (-1V typ.).
5. SW1 and SW2 - Selection switches to adjust the clock delay. These switches enable the clock delay to be stepped to any one of 23 settings through binary input. Binary input from 00001 to 00110 increments the clock delay at approximately 125ps intervals. Binary input from 00111 to 10111 increments the clock delay at approximately 190ps intervals. The switches are designed such that, when SW1 is normally set to 1010 or A in hexadecimal, and SW2 is either set to L or not mounted, good timing margin can be achieved at any clock frequency.
6. SW3 (Decimation) - The switch to select clock frequency decimation. Selection settings are as follows:

NO.	DECIMATION RATE
0	1/1
1	1/2
2	1/4
3	1/8
4	1/16
5	1/32
6	1/64
7	1/128

7. SW4 - The switch for MINV High/Low
8. SW5 - The switch for LINV High/Low
9. SW6 (D/A INV) - The switch for D/A converter output inversion
10. Pins P4 to P33 facilitate probe GND connection. As shown in the Figure 2, the distance between the probe point and the GND is 300 mils, and there is 1.2mm throughhole for each probe point. The signal and GND locations are designed for use with a Tektronix GND tip (part number 013-1185-00).
11. D/A converter (IC11) input data (waveform probe pins P24 to P31) are the complementary signals of the decimated A/D converter outputs. These are inverted again in the D/A converter so that the polarity of the reproduced waveform matches the analog input to the A/D.

12. When observing the reproduced waveform (DA OUT output), set the decimator so that the clock frequency of the D/A converter (IC11: HI20201JCB) is less than 100MHz.
13. The part number of the digital output connector is KEL 8830E-020-170S. A corresponding connector and cable assembly is JUNKOSHA KB0020MCG50B1.
14. The buffer used on the evaluation board will give the best available performance. However, it is an expensive part and requires ± 15 V supplies. The circuit in Figure 3 is a much lower cost solution. It will have a bandwidth of about 250MHz with a slightly degraded SNR performance at higher input frequencies. It will provide a gain of approximately -2 and V_{OFFSET} can be driven from the same offset circuit used on the evaluation board.

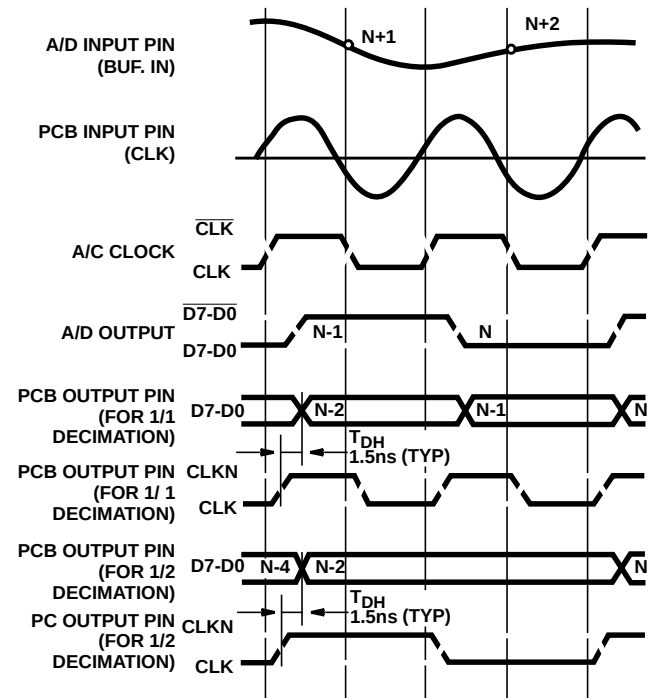


FIGURE 1.

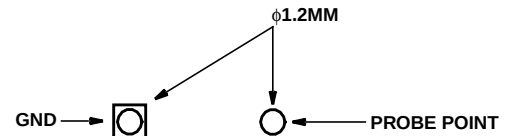


FIGURE 2.

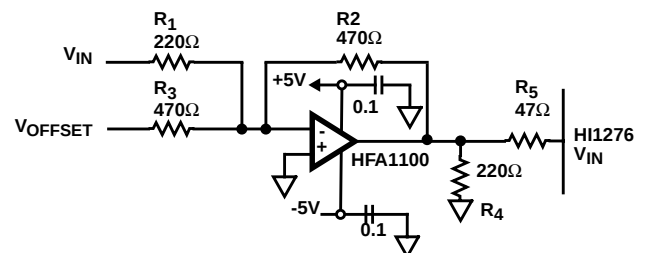


FIGURE 3. INVERTING BUFFER

Typical Performance Curves

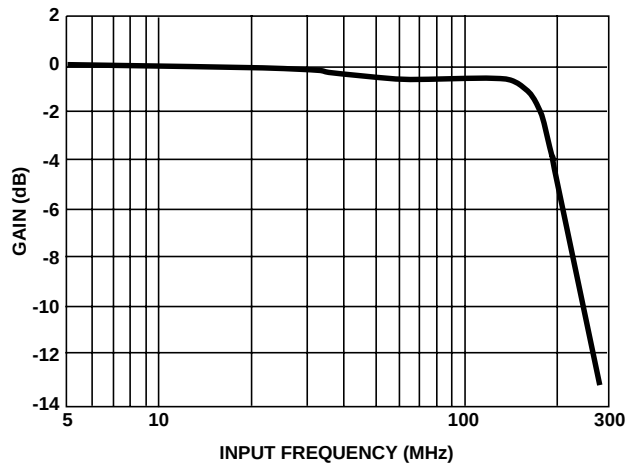


FIGURE 4. GAIN vs INPUT FREQUENCY

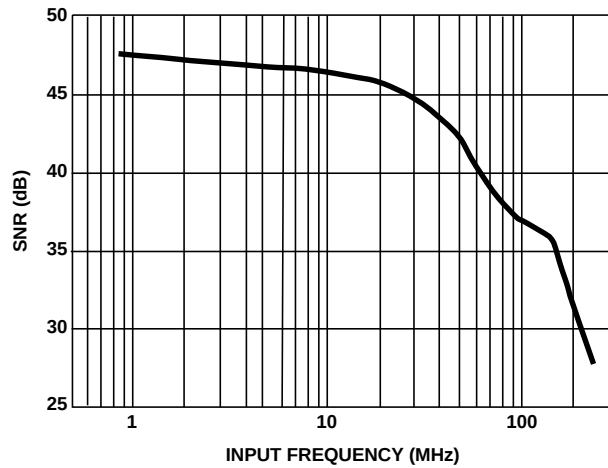


FIGURE 5. SNR vs INPUT FREQUENCY

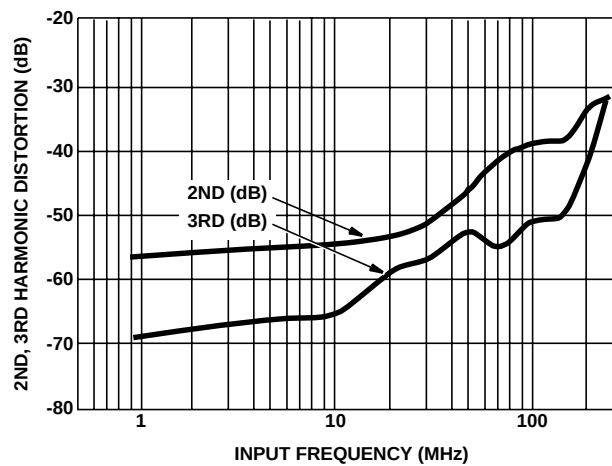
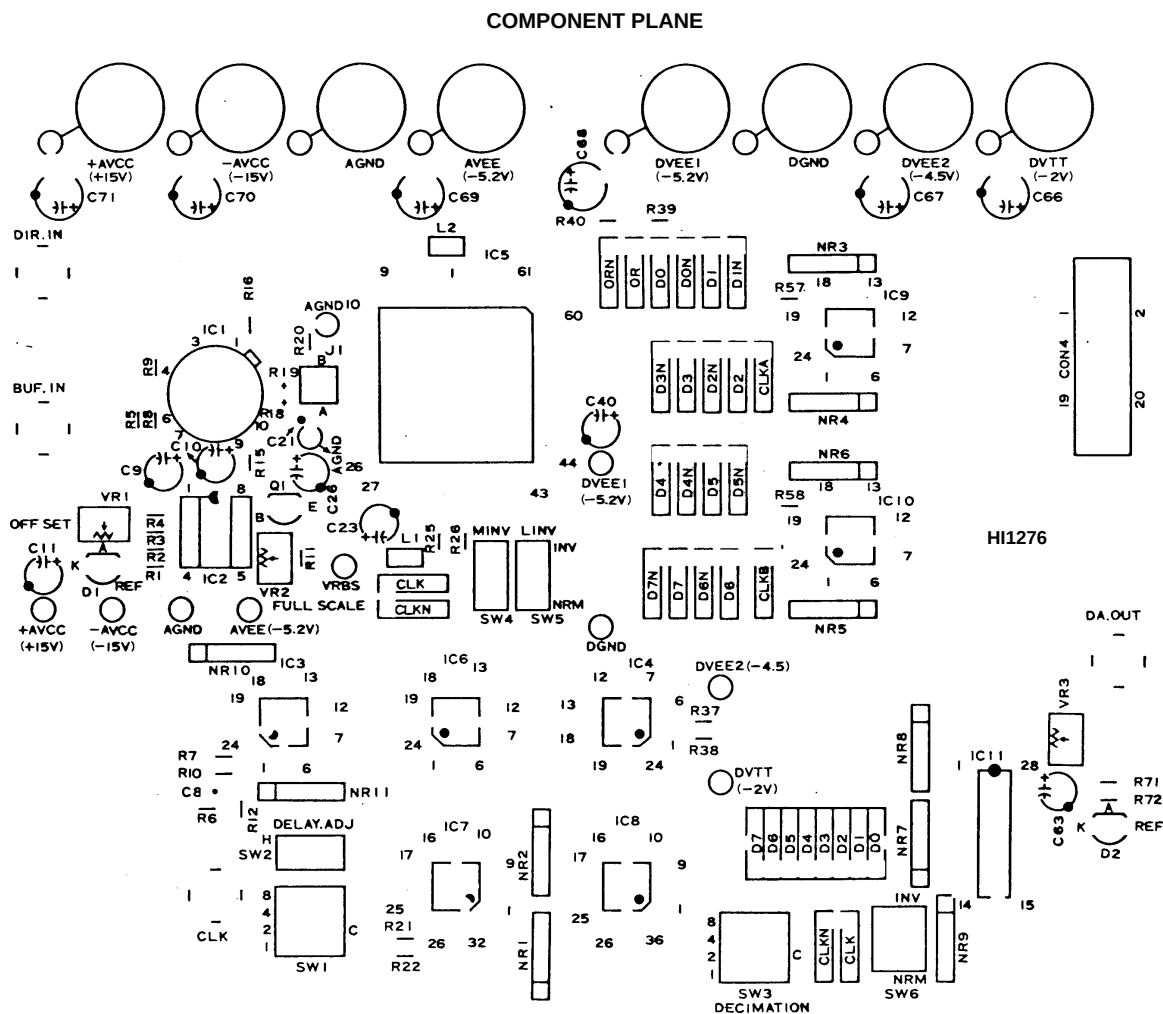


FIGURE 6. 2ND, 3RD HARMONIC DISTORTION vs INPUT FREQUENCY

Parts Layout



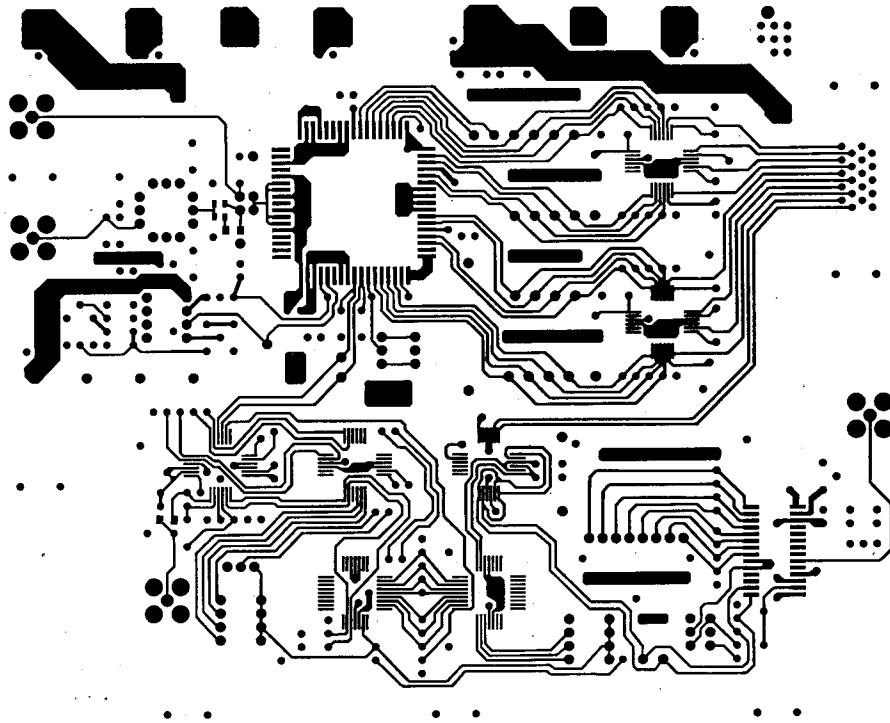
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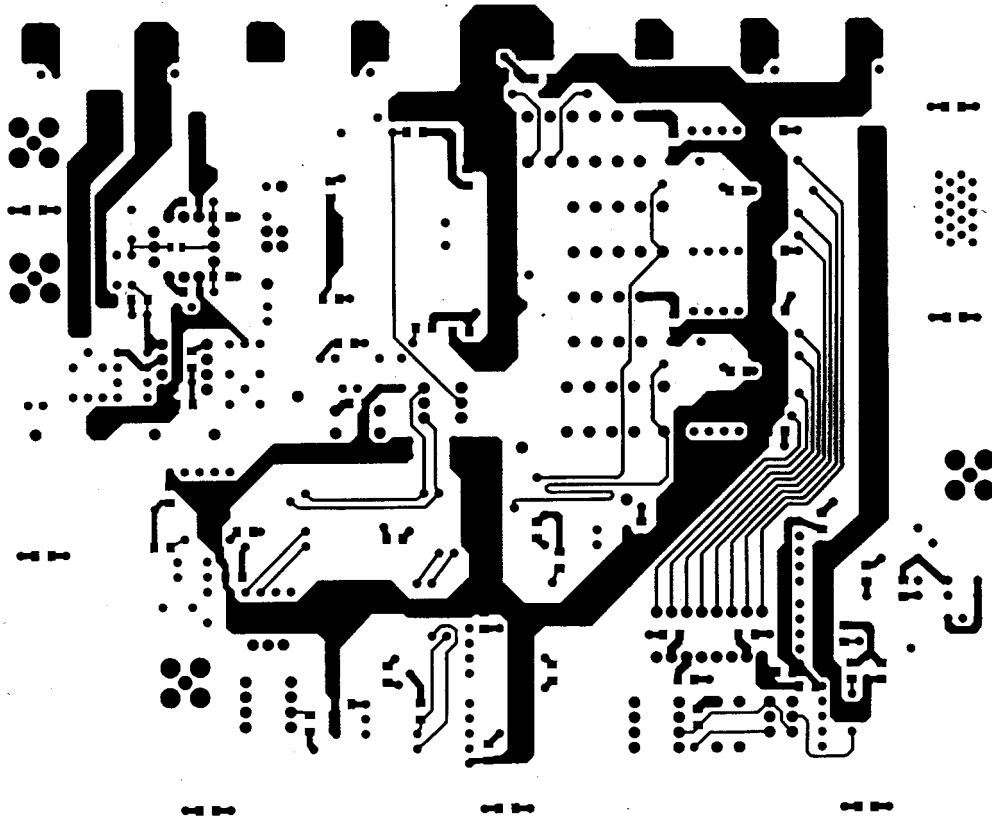
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Print Pattern

COMPONENT PLANE

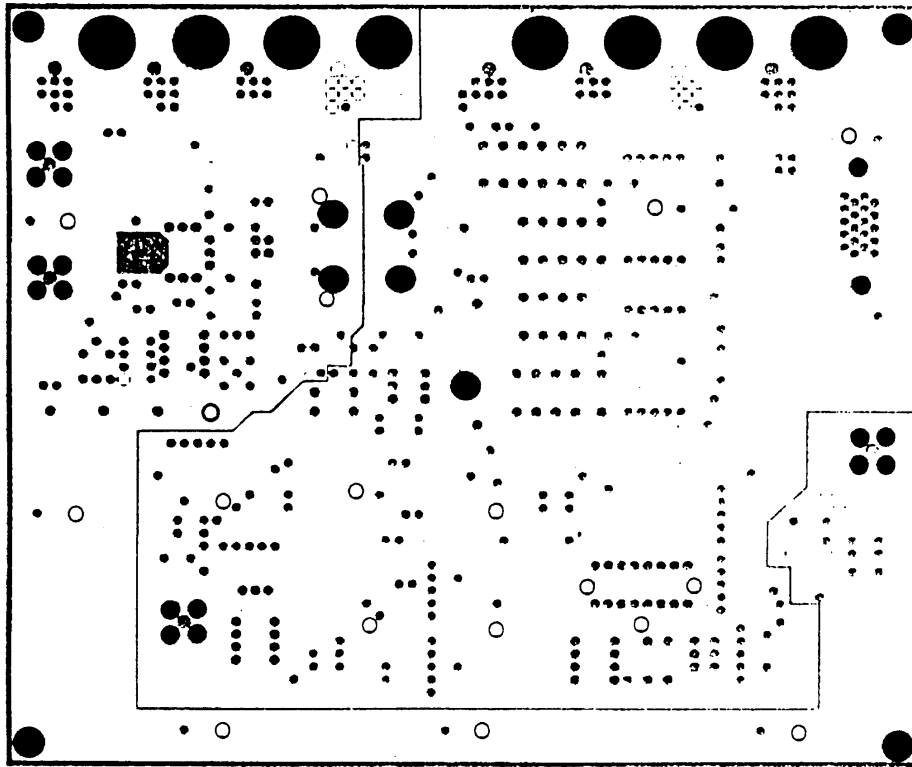


SOLDER PLANE

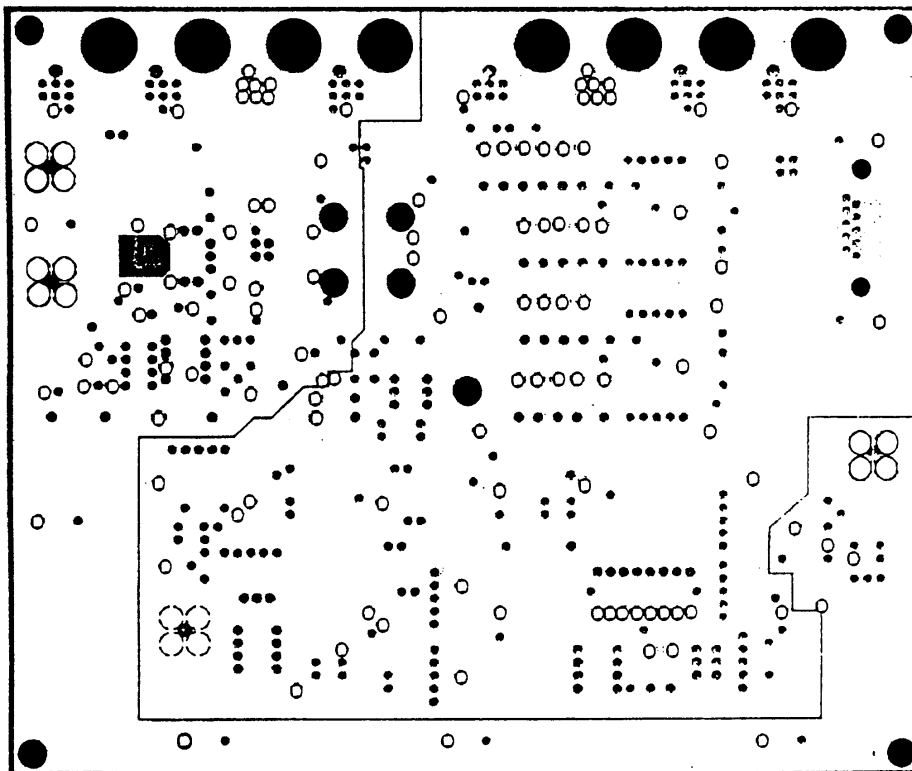


Print Pattern (Continued)

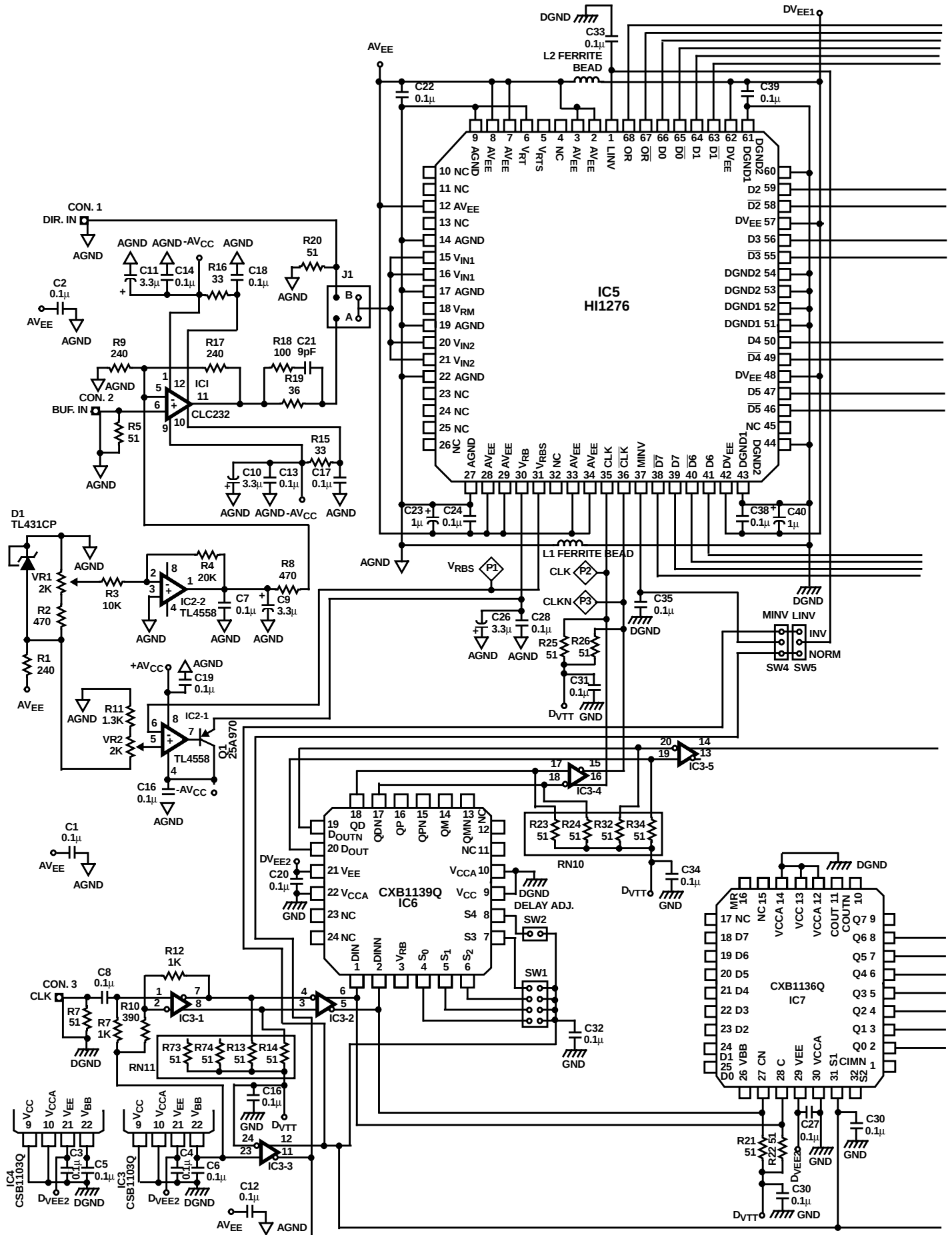
GND PLANE (INNER LAYER)



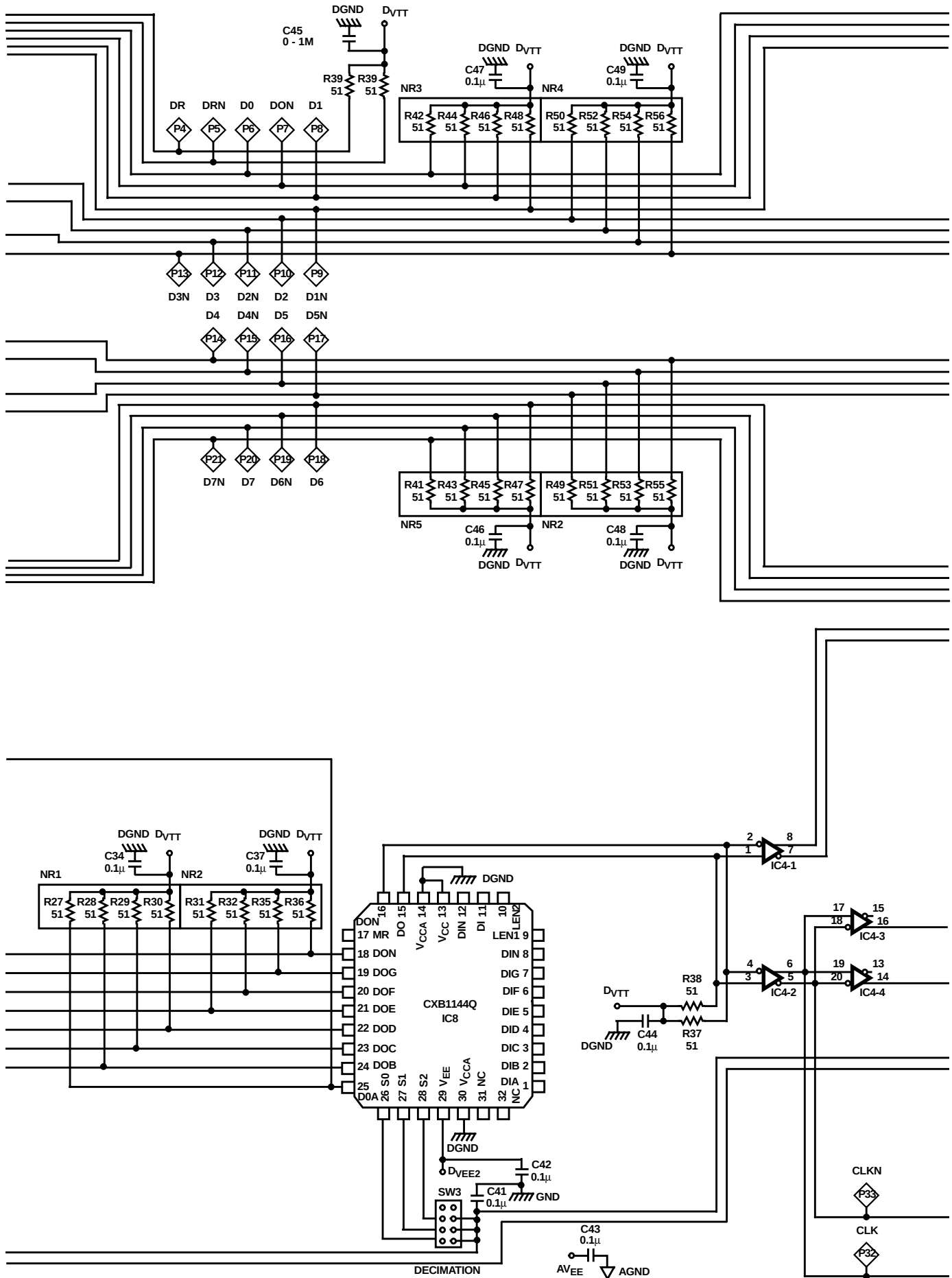
VEE LAYER (INNER LAYER)



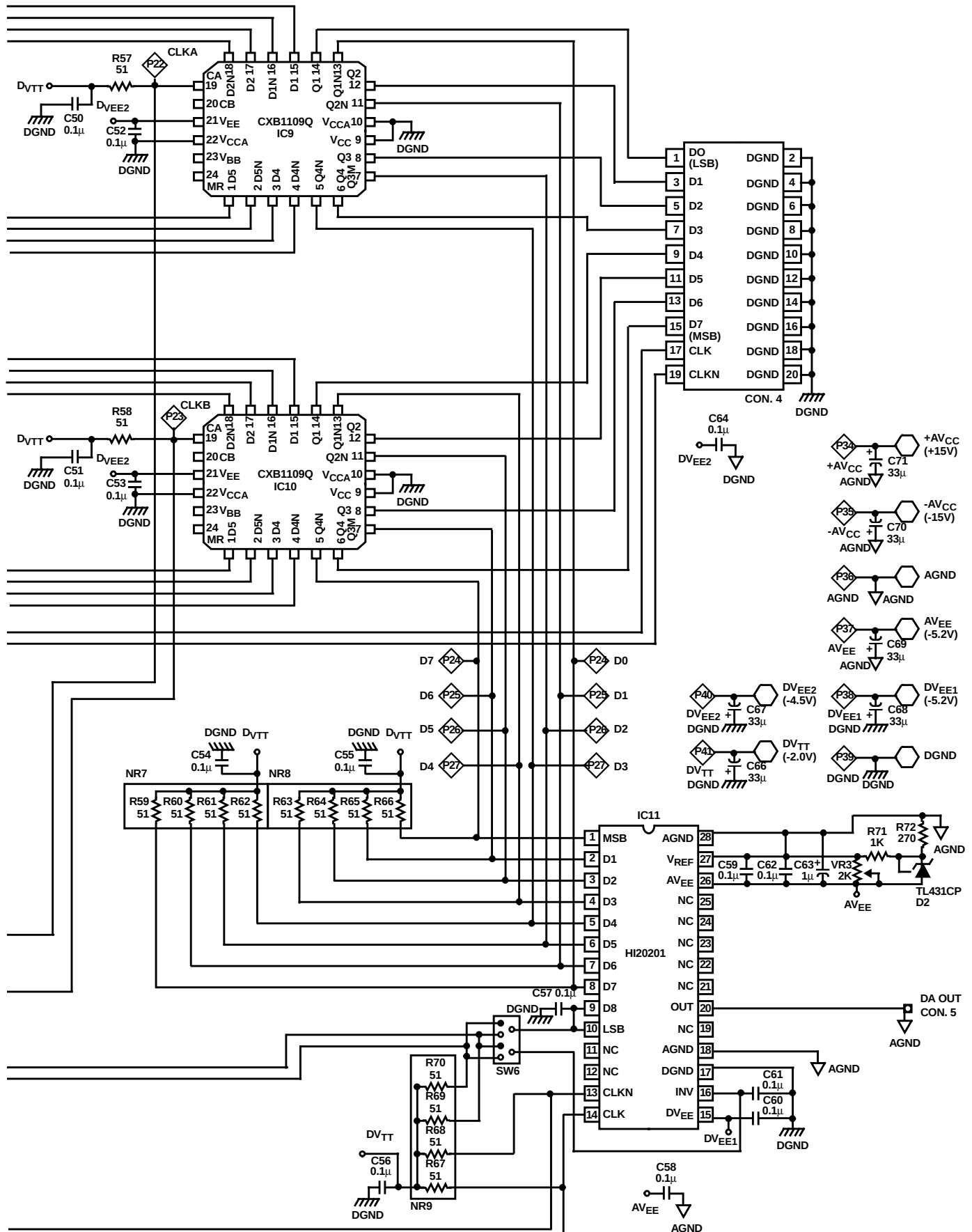
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